Form PTO-1595 (Rev. 09/ 04) OMB No. 0651-0027 (exp. 6/30/2005)	U.S. DEPARTMENT OF COMMER United States Patent and Trademark Of
RECORDATION FO	RM COVER SHEET
PATENTS ONLY	
To the Director of the U.S. Patent and Trademark Office: Pleas	se record the attached documents or the new address(es) below
Name of conveying party(ies)/Execution Date(s):     TAKEO MORINAGA (1/9/2007) AND ICHIRO HAMADA (1/12/2007)	2. Name and address of receiving party(ies)
Execution Date(s): in parentheses after inventor name  Additional name(s) of conveying party(les) attached?  Yes X No  3. Nature of Conveyance:  X Assignment	Name: SONY CORPORATION Internal Address: Street Address: 7-35, Kitashinagawa 6-chome Shinagawa-ku Tokyo 141-0001 JAPAN City: State: Country: Zip: Additional name(s) & address(es) Yes x No attached: This document is being illed together with a new application. B. Patent No.(s)
Additional numbers attached?  Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and
Name: Dennis M. Smid, Esq. LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
Internal Address: Atty. Dkt.:	Authorized to be charged by credit card
Street Address: 600 South Avenue West	Authorized to be charged to deposit account     Enclosed     None required (government interest not affecting title)
City: Westfield	8. Payment Information
State: NJ Zip: 07090	a. Credit Card Last 4 Numbers
Phone Number: (908) 518-6374	Expiration Date
Fax Number: (908) 654-0415 Email Address: dsmid@ldlkm.com	b. Deposit Account Number 12-1095 Authorized User Name Dennis M. Smid, Esq.
Signature:	Dennis M. Sima, Esq.
Ca mill	January 17, 2007
€ Signature	Date
Dennis M. Smid, Esq 34,930	Total number of pages including cover
Name of Person Signing	sheet, attachments, and documents:

Docket No.: SONYJP 3.0-689

**PATENT** 

**REEL: 018783 FRAME: 0866** 

Docket No.: SONYJP 3.0-689

Sony Ref. No.: S06P1316US00

## ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in:

## TRANSMISSION/RECEPTION SYSTEM, RECORDING APPARATUS AND METHOD, PROVIDING APPARATUS AND METHOD, AND PROGRAM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, my entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the application number and filing date of this application in the spaces that follow: Application Number: 11/589,511; Filing Date: October 30, 2006.

This assignment executed on the dates indicated below.

Takeo Morinaga	
Name of First or Sole Inventor	Execution Date of U.S. Patent Application
Kanagawa, Japan	
Residence of First or Sole Inventor	····
Taken Morinage	January 9, 2007
Signature of First or Sole Inventor	Date of this Assignment

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Docket No.: SONYJP 3.0-689 Sony Ref. No.: S06P1316US00

Ichiro Hamada	
Name of Second Joint Inventor	Execution Date of U.S. Patent Application
Kanagawa, Japan	
Residence of Second Joint Inventor	
John Hamada	January 12, 2007
Signature of Second Joint Inventor	Date of this Assignment

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PATENT REEL: 018783 FRAME: 0868